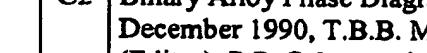
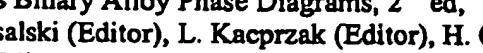


<b>Form 1449 (Modified)</b>	Atty Docket No. <b>ALTRP084C1</b>	Application No.: <b>Not yet assigned</b>
<b>Information Disclosure Statement By Applicant</b>	Applicant: <b>My Nguyen</b>	<b>101775370</b>
(Use Several Sheets if Necessary)	Filing Date <b>February 9, 2004</b>	Group <b>2825</b> Not yet assigned

## **U.S. Patent Documents**

### **Foreign Patent or Published Foreign Patent Application**

## **Other Documents**

Other Documents		
Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1	Goyal, et al, "Failure Mechanism of Brittle Solder Joint Fracture in the Presence of Electroless Nickel Immersion Gold (ENIG) Interface", Proceedings of the 52 <sup>nd</sup> Electronic Component and Technology Conference, 732-739, May 2002.
	C2	Binary Alloy Phase Diagrams Binary Alloy Phase Diagrams, 2 <sup>nd</sup> ed, December 1990, T.B.B. Massalski (Editor), L. Kacprzak (Editor), H. Okamoto (Editor), P.R. Subramanian (Editor), pgs 2269, 2642, 2644, 2294, 2996, 1449, 1451, 1746-1748.
Examiner		Date Considered  12/20/2021 - 10/1

**Examiner:** Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.